

NDS Compliant

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 16.15L x 16.90W x 2.60H mm
Weight: Approx. 0.85 g
Contact principle: Friction technology
Operating position: Shaft up / Down / Horizontal
Mounting System: SMT Type (without post)
Durability: 5,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0
RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

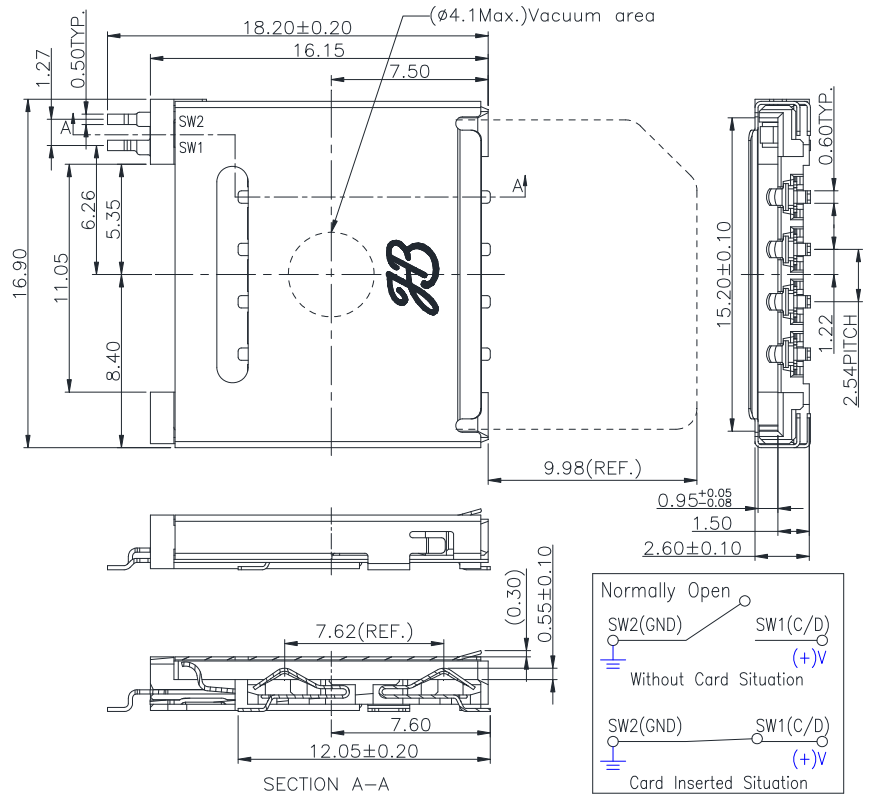
Number of contacts: 8 pins
Contact resistance: 50 mΩ typical, 100 mΩ max.
Insulation resistance: >1000 MΩ / 500 VDC
Switch type: Blade
Operation: Normally Open

4. Solderability

Wave: Not applicable
IR reflow: 260°C, 10 sec. Max.
Manual soldering: 360°C, 3 sec. Max.

5. Environmental Characteristics

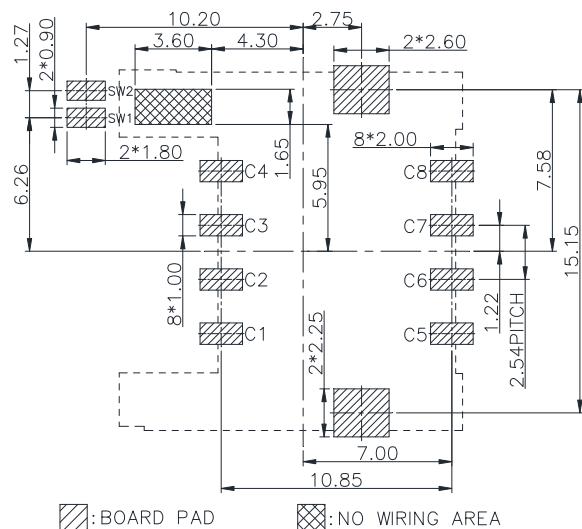
Operating temperature: - 40°C ~ + 90°C
Operating humidity: 10 % ~ 95 % RH
Storage temperature: - 40°C ~ + 90°C
Storage humidity: 10 % ~ 95 % RH



※Metal cover can't be pressed. Must keep 0.1 mm min. gap above cover.

Unit: mm; Tolerances: ±0.15 mm

Mechanical outline dimension



▨: BOARD PAD ▩: NO WIRING AREA

Unit: mm; Tolerances: ±0.05 mm
Reference dimension for PCB layout

Note:

1. Coplanarity of solder pins 0.10mm max.
2. Recommended thickness of solder paste > 0.15mm.

HB SIM Card Connector

Model No.: ICC-324

Revision: 0.9 Date: JAN. 03, 2018